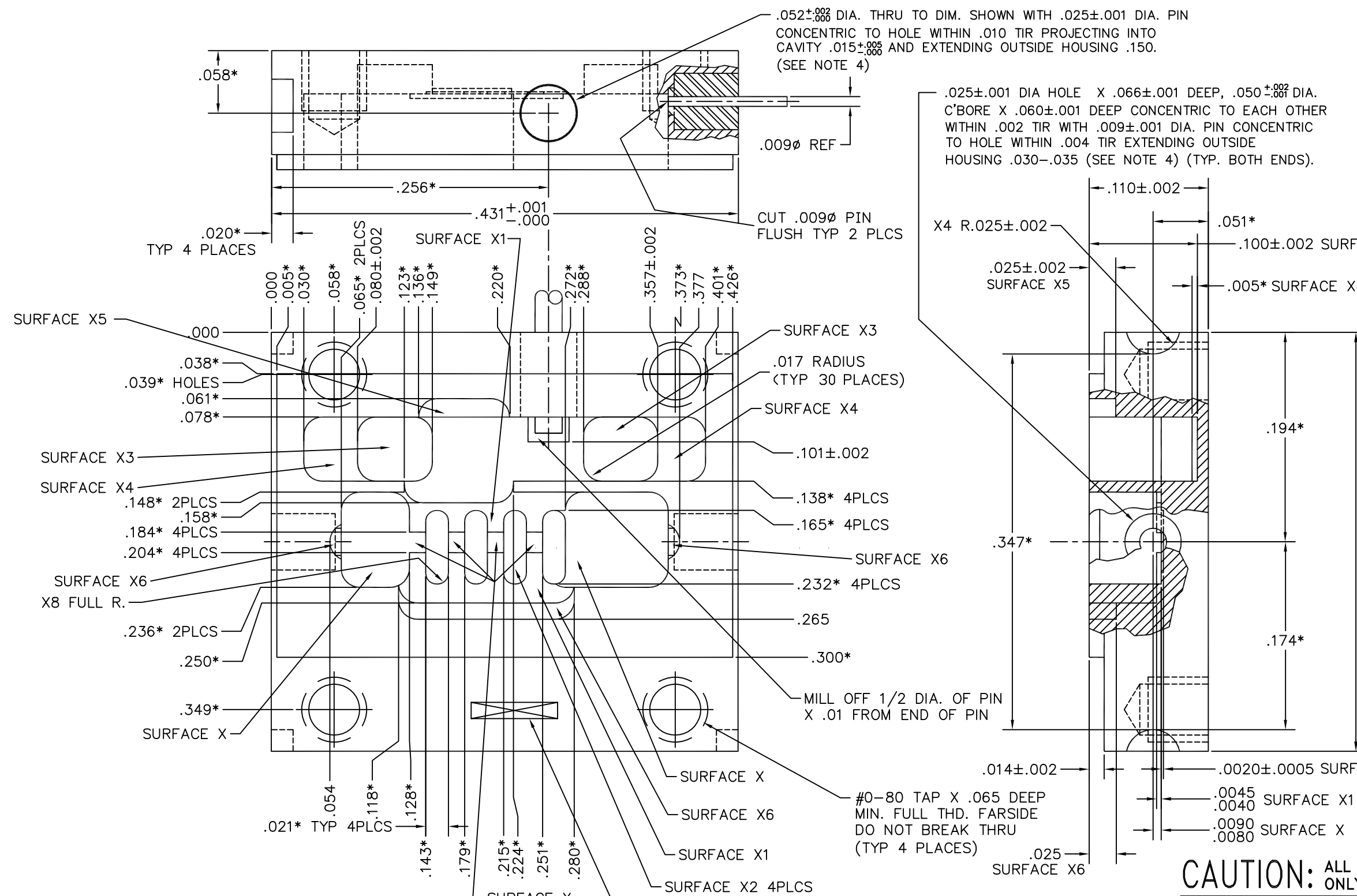


REVISIONS				
ZONE	LTR	DESCRIPTION	DATE	APPROVAL
	A	INITIAL RELEASE	08/10/96	
	B	MOVED #0-80 TAP HOLES INBOARD	EM 08/26/96	
	C	ZONE: (D7&D8) DEL '.002 X .100 STEP' ZONE: (C8).184* WAS .185*, (B8).204* WAS .203*	EM 10/30/96	
	D	ZONE: (C7) DIM .064* ADDED 'TYP'; ZONE (C5) EM DEL. DIM '.366*'; ZONE (D4) .060 DP. WAS .058 DP.; ZONE (A7,8) CHG STEEL STMP TO LASER MRK	EM 03/27/97	
	E	ZONE: C7 CHG DIM'S .061* WAS .071*, .038* WAS .048; ZONE C4 .025±.002 WAS .047±.002	EM 09/12/97	



CAUTION: ALL DIMENSIONS, INCLUDING TAPPED HOLES, APPLY ONLY AFTER PLATING! - SEE NOTE 1 FOR FINISH

NOTE:

1. FINISH: ALL DIMENSIONS ARE TAKEN AFTER PLATING. ELECTROLESS NICKEL PLATE 100/200 MICRO INCHES THICK PER MIL-C-26074, GOLD PLATE 50-80 MICRO INCHES THICK MIN. PER MIL-G-45204 CLASS 1, TYPE 3 GRADE A.
2. GLASS SEAL SHALL FILL .052 DIA AND .078/.080 DIA. AND SHALL NOT PROTRUDE BEYOND WALL NOR HAVE AN INDENTATION EXCEEDING .020 ±.010.
3. LEAKAGE THROUGH HERMETIC SEALS IN EXCESS OF 5 x 10⁻⁸ CC/SEC OF HELIUM SHALL BE CAUSE FOR REJECTION.
4. CHIP OUTS (AREAS WHERE MENISCUS CRACKS PERMIT BREAKAWAY OF GLASS) SHALL BE CAUSE FOR REJECTION. IF THE CHIP OUT EXPOSES MORE THAN .010 INCHES OF BASE METAL OF THE PIN AND/OR IF THE CHIP OUT EXTENDS MORE THAN 50% OF THE DISTANCE FROM PIN TO CASE OR CASE TO PIN.
5. FOR COVER SEE DRAWING 128822.
6. DIMENSIONS MARKED WITH AN ASTERISK (*) ARE ±.001.

SYM	DESCRIPTION	QTY	NEXT ASSY	USED ON
	HOLE DATA TABLE			
	APPLICATION			

QTY REQ'D		NOMENCLATURE OR DESCRIPTION	SYM/NOTES	PART NO.	CODE IDENT.	ITEM NO.
PARTS LIST						
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON		DRN BY <i>Ed. Macky</i> NAME DATE		 100 Davids Drive, Hauppauge, New York 11788		
DECIMALS .XX±.01 ANGLES .XXX±.005 ±0°30'		APPROVED BY		HOUSING DRAWING, JSA1A AMPLIFIER, 4 STAGE		
MATERIAL MAKE FROM KOVAR PER MIL-I-23011		PROJ ENGR		SIZE CODE IDENT. NO D 33592 128745		
FINISH SEE NOTE 1		Q.A.		SCALE 20:1 REF 80D000 (2640) SHEET 1 OF 1		
HEAT TREAT				REV. E		

128745